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MEG-02-005

U.S. Patent 6,291,268 to Ho, "Low Cost Method of Testing a Cavity-Up BGA Substrate," discloses a method for testing a BGA substrate.

U.S. Patent 6,162,652 to Dass et al., "Process for Sort Testing C4 Bumped Wafers," describes a method of cleaning and testing bumped wafers.

U.S. Patent 6,143,668 to Dass et al., "KLXX Technology with Integrated Passivation Process, Probe Geometry and Probing Process," describes a wafer testing method utilizing cleaning of bond pads prior to testing.

Sincerely,



Stephen B. Ackerman,
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